

1.5V Drive Pch MOSFET

QS8J2

Structure

Silicon P-channel MOSFET

● Features

- 1) Low On-resistance.
- 2) High power package.
- 3) 1.5V drive.

Application

Switching

Packaging specifications

	<u> </u>	
Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
QS8J2		0

● Absolute maximum ratings (Ta = 25°C)

Parameter		Symbol	Limits	Unit
Drain-source voltage		V_{DSS}	-12	V
Gate-source voltage		V_{GSS}	±10	V
Drain current	Continuous	I _D	±4	Α
	Pulsed	I _{DP} *1	±12	Α
Source current (Body Diode)	Continuous	l _s	-1	Α
	Pulsed	I _{sp} *1	-12	Α
Power dissipation		P _D *2	1.5	W / TOTAL
		·В	1.25	W / ELEMENT
Channel temperature		Tch	150	°C
Range of storage temperature		Tstg	-55 to +150	°C

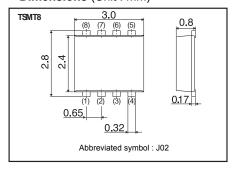
^{*1} Pw≤10μs, Duty cycle≤1%

• Thermal resistance

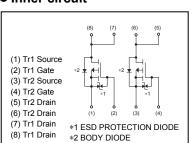
Parameter	Symbol	Limits	Unit		
Channel to Ambient	Rth (ch-a)*	83.3	°C/ W /TOTAL		
Channel to Ambient	Kui (Gii-a)	100	.3 °C/W/TOTAL		

^{*} Mounted on a ceramic board.

● Dimensions (Unit : mm)



• Inner circuit



^{*2} Mounted on a ceramic board.

● Electrical characteristics (Ta = 25°C)

<It is the same ratings for Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	1	-	±10	μA	$V_{GS}=\pm 10V$, $V_{DS}=0V$
Drain-source breakdown voltage	V _{(BR)DSS}	-12	-	-	٧	$I_D = -1 \text{mA}, V_{GS} = 0 \text{V}$
Zero gate voltage drain current	I _{DSS}	1	-	-1	μA	$V_{DS}=-12V$, $V_{GS}=0V$
Gate threshold voltage	V _{GS (th)}	-0.3	-	-1.0	٧	$V_{DS}=-6V$, $I_{D}=-1mA$
	*	1	26	36		$I_D = -4A, V_{GS} = -4.5V$
Static drain-source on-state		1	36	50	mΩ	$I_D = -2A, V_{GS} = -2.5V$
resistance	R _{DS (on)}	1	46	69	11152	I _D =-2A, V _{GS} =-1.8V
		1	66	132		$I_D = -0.8A, V_{GS} = -1.5V$
Forward transfer admittance	IY _{fs} I*	5.5	-	-	S	$I_D=-4A$, $V_{DS}=-6V$
Input capacitance	C _{iss}	1	1940	-	pF	V _{DS} =-6V
Output capacitance	C _{oss}	1	260	-	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	1	240	-	pF	f=1MHz
Turn-on delay time	t _{d(on)} *	1	10	-	ns	I _D =-2A, V _{DD} ≒ -6V
Rise time	t _r *	1	60	-	ns	V _{GS} =-4.5V
Turn-off delay time	t _{d(off)} *	1	300	-	ns	R _L ≒3Ω
Fall time	t _f *	1	180	-	ns	$R_G=10\Omega$
Total gate charge	Q _g *	-	20	-	nC	I _D =-4A, V _D ;≒ -6V
Gate-source charge	Q _{gs} *	-	3.5	-	nC	V _{GS} =-4.5V R _L ≒1.5Ω
Gate-drain charge	Q _{gd} *	-	3.0	-	nC	$R_G=10\Omega$

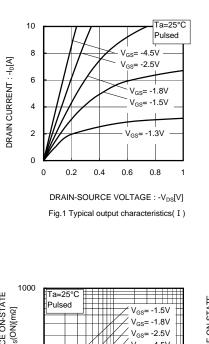
^{*}Pulsed

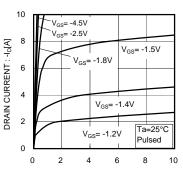
●Body diode characteristics (Source-Drain) (Ta = 25°C)

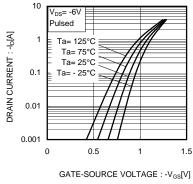
<It is the same ratings for Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V _{SD} *	-	-	-1.2	V	$I_s=-4A$, $V_{GS}=0V$

^{*}Pulsed







DRAIN-SOURCE VOLTAGE : -V_{DS}[V]
Fig.2 Typical output characteristics(II)

GATE-SOURCE VOLTAGE : -V_{GS}[V] Fig.3 Typical Transfer Characteristics

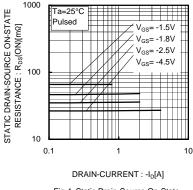


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

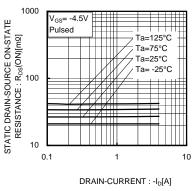


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

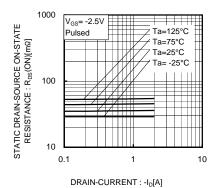
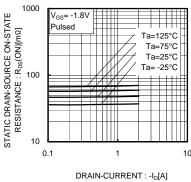


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(Ⅲ)



DRAIN-CURRENT : -I_D[A]
Fig.7 Static Drain-Source On-State
Resistance vs. Drain Current(Ⅳ)

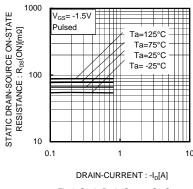


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(V)

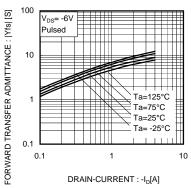
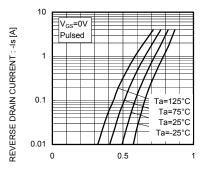
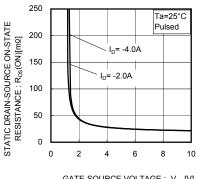


Fig.9 Forward Transfer Admittance vs. Drain Current



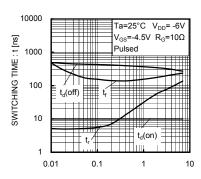
SOURCE-DRAIN VOLTAGE : - V_{SD} [V]

Fig.10 Reverse Drain Current vs. Sourse-Drain Voltage



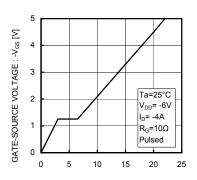
 $\mathsf{GATE}\text{-}\mathsf{SOURCE}\;\mathsf{VOLTAGE}: \text{-}\mathsf{V}_\mathsf{GS}[\mathsf{V}]$

Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

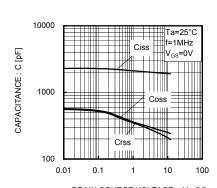


 $\mathsf{DRAIN}\text{-}\mathsf{CURRENT}: \mathsf{-}\mathsf{I}_\mathsf{D}[\mathsf{A}]$

Fig.12 Switching Characteristics



TOTAL GATE CHARGE: Qg [nC] Fig.13 Dynamic Input Characteristics



DRAIN-SOURCE VOLTAGE : $-V_{DS}[V]$ Fig.14 Typical Capacitance

vs. Drain-Source Voltage

Measurement circuits

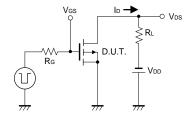


Fig.1-1 Switching Time Measurement Circuit

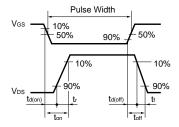


Fig.1-2 Switching Waveforms

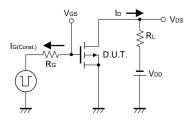


Fig.2-1 Gate Charge Measurement Circuit

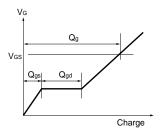


Fig.2-2 Gate Charge Waveform

Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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